

LTVS23H712CLT1G

ESD Protection Diodes

1. FEATURES

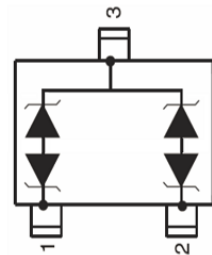
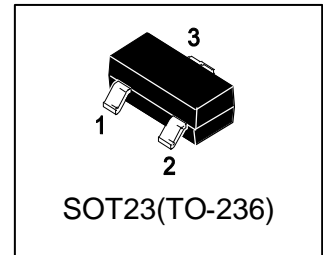
- Low capacitance.
- Low clamping voltage.
- ESD protection
- Complies with IEC 61000-4-2 standards: Air discharge: $\pm 30\text{kV}$
Contact discharge: $\pm 30\text{kV}$
- We declare that the material of product compliance with RoHS requirements and Halogen Free.

2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LTVS23H712CLT1G	DM	3000/Tape&Reel

3. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
IEC 61000-4-2 (ESD)	Contact	± 30	kV
	Air	± 30	
peak pulse power @ 8/20 μs	PPP	400	W
peak pulse current @ 8/20 μs	IPP	17	A
Storage Temperature Range	Tstg	$-55 \sim +150$	$^\circ\text{C}$
Operating Temperature Range	TJ	$-55 \sim +125$	$^\circ\text{C}$



4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	MIN	MIN	MAX	Unit
Reverse stand-off voltage (Pin 1、 2 to Pin 3) (Pin 3 to Pin 1、 2)	VRWM	-	-	12 7	V
Reverse breakdown voltage (IT = 1 mA, Pin 1、 2 to Pin 3) (IT = 1 mA, Pin 3 to Pin 1、 2)	VBR	13.3 7.5	- -	- -	V
Reverse leakage current (VR = VRWM, Pin 1、 2 to Pin 3) (VR = VRWM, Pin 3 to Pin 1、 2)	IR	- -	- -	100 200	nA
Clamping Voltage (IPP = 5A (8 x 20µs pulse), Pin 1、 2 to Pin 3) (IPP = 5A (8 x 20µs pulse), Pin 3 to Pin 1、 2) (IPP = 17A (8 x 20µs pulse), Pin 1、 2 to Pin 3) (IPP = 17A (8 x 20µs pulse), Pin 3 to Pin 1、 2)	VC	- - - -	- - - -	18 12 23 15	V
Junction Capacitance (VR = 0V, f = 1MHz, Pin 1、 2 to Pin 3) (VR = 0V, f = 1MHz, Pin 3 to Pin 1、 2) (VR = VRWM, f = 1MHz, Pin 1、 2 to Pin 3) (VR = VRWM, f = 1MHz, Pin 3 to Pin 1、 2)	CJ	- - - -	- - 32 35	75 75 - -	pF

5. ELECTRICAL CHARACTERISTICS CURVES

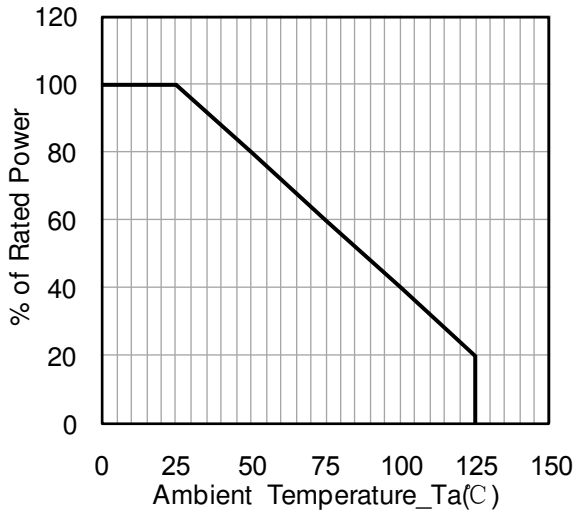


Figure 1. Power Derating Curve

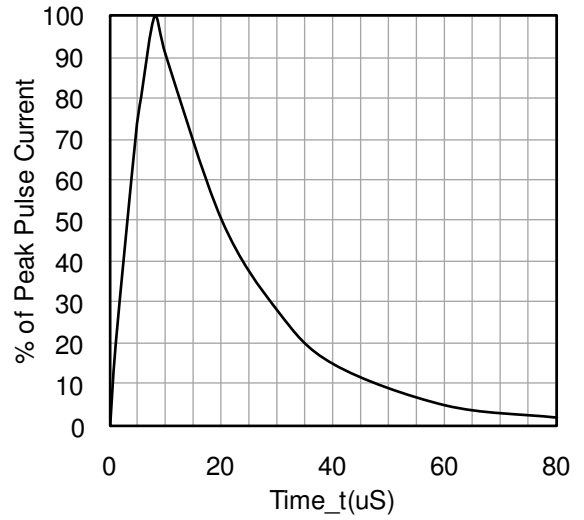


Figure 2. 8 X 20uS Pulse Waveform

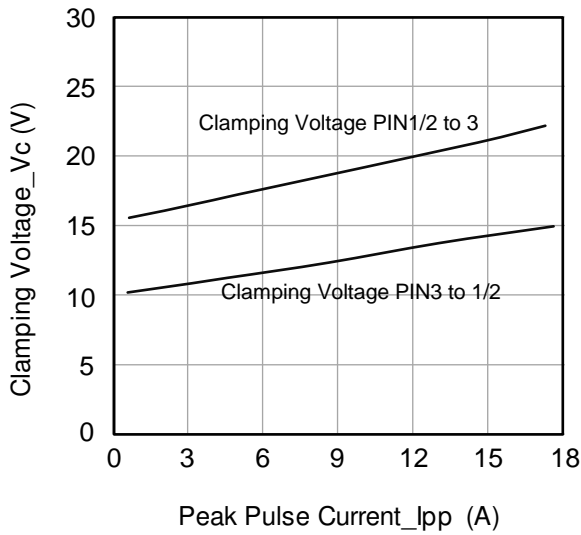


Figure 3. Clamping Voltage vs. Peak Pulse Current

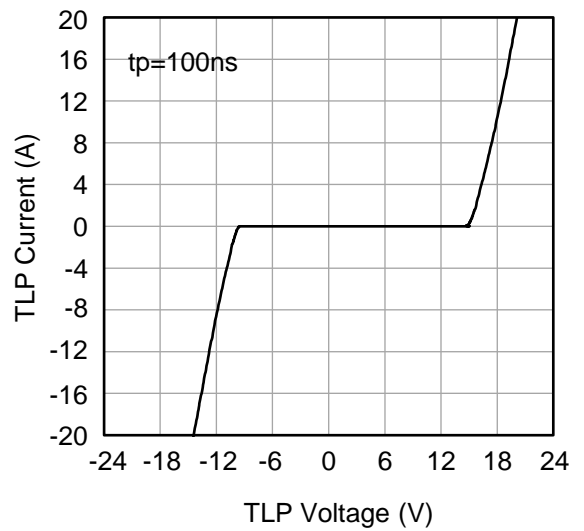
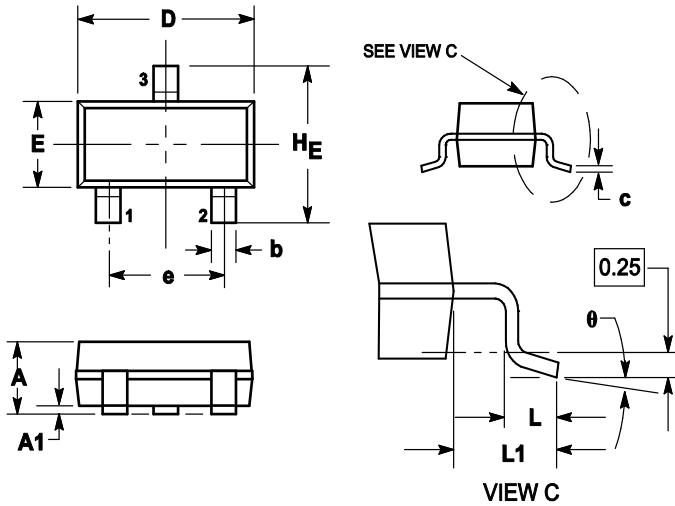


Figure 4. TLP Measurement

6. OUTLINE AND DIMENSIONS

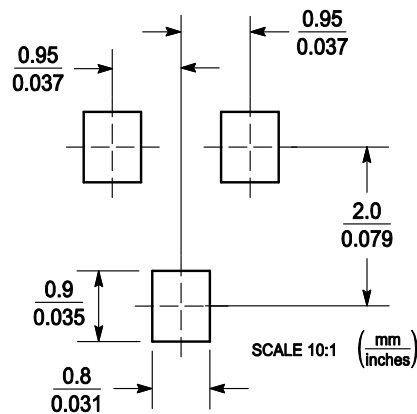
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

7. SOLDERING FOOTPRINT



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